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**CARDXX ANNOUNCES PATENT PENDING STATUS FOR MEMORY MODULES, KEY FOBS,
AND RFID INTELLIGENT DOCUMENTS**

Englewood, Colorado - CardXX, Inc. (CXCQ.PK), a leading smart card manufacturer, today announced that the Company has expanded its current patent portfolio and added several new technologies that are patent pending, including patents in the areas of Memory Module Assembly, Intelligent Key Fob Assembly, and RFID Enabled Document Assembly. The pending patents will enable the Company to expand into additional industry segments.

CardXX has developed patented technologies to securely encapsulate electronics into Smart Cards and other portable devices or form factors. The CardXX process offers the following unique advantages:

- Injected thermoset polymer encapsulates and protects all electronic elements completely and securely
- Low-temperature and low-pressure process prevents damage to delicate electronics and improves manufacturing yield
- Superior heat resistance and chemical resistance protects against physical and chemical attacks
- Physical access to chip electronics is difficult to obtain without severe damage or destruction of the chip
- Multiple materials can be used for exterior skins including paper for all form factors

ABOUT CARDXX

CardXX provides secure encapsulation of advanced electronics through manufacturing and licensing secure and intelligent Smart Cards using its proprietary, patented encapsulation process known as the Reaction Assisted Molded Process (RAMP).

The Statements contained in this release that are not purely historical are forward-looking statements within the Private Securities Litigation Reform Act of 1995 and are subject to various risks, uncertainties and other factors that could cause the Company's actual results, performance or achievements to differ materially from those expressed or implied by such forward-looking statements. Forward looking statements include, but are not limited to, those relating to demand for the Company's services, expected demand for our services and expectations regarding our revenues, the Company's ability to continue to utilize goodwill, to continue to increase gross margins, to achieve and manage growth, to develop and market new applications and services, risks relating to the acquisition and integration of acquired businesses, demand for new services and applications, timing of demand for services, industry strength and competition and general economic factors. Investors are directed to consider such risks, uncertainties and other factors described in documents filed by the Company with the Securities and Exchange Commission.